

HD74LS06

Hex Inverter Buffers / Drivers
(with Open Collector High-Voltage Output)

REJ03D0392-0200

Rev.2.00

Feb.18.2005

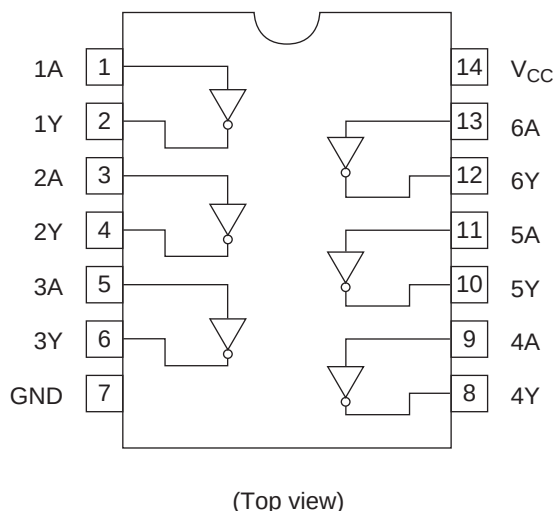
Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS06P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS06FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)
HD74LS06RPEL	SOP-14 pin (JEDEC)	PRSP0014DE-A (FP-14DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V_{CC} ^{Note}	7	V
Input voltage	V_{IN}	7	V
Output voltage	V_{OUT}	30	V
Power dissipation	P_T	400	mW
Operating temperature range	T_{opr}	-20 to +75	°C
Storage temperature	T_{stg}	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.75	5.00	5.25	V
Output voltage	V_{OH}	—	—	30	V
Output current	I_{OL}	—	—	48	mA
Operating temperature	T_{opr}	−20	25	75	°C

Electrical Characteristics

(Ta = −20 to +75 °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V_{IH}	2.0	—	—	V	
	V_{IL}	—	—	0.8	V	
Output voltage	V_{OL}	—	—	0.4	V	$I_{OL} = 24 \text{ mA}$ $I_{OL} = 48 \text{ mA}$ $V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}$
		—	—	0.5		
Input current	I_{IH}	—	—	20	μA	$V_{CC} = 5.25 \text{ V}, V_I = 2.7 \text{ V}$
	I_{IL}	—	—	−0.4	mA	$V_{CC} = 5.25 \text{ V}, V_I = 0.4 \text{ V}$
	I_I	—	—	0.1	mA	$V_{CC} = 5.25 \text{ V}, V_I = 7 \text{ V}$
Output current	I_{OH}	—	—	250	μA	$V_{CC} = 4.75 \text{ V}, V_{IL} = 0.8 \text{ V}, V_{OH} = 30 \text{ V}$
Supply current	I_{CCH}	—	23	48	mA	$V_{CC} = 5.25 \text{ V}$
	I_{CCL}	—	21	51	mA	$V_{CC} = 5.25 \text{ V}$
Input clamp voltage	V_{IK}	—	—	−1.5	V	$V_{CC} = 4.75 \text{ V}, I_{IN} = -18 \text{ mA}$

Note: * $V_{CC} = 5 \text{ V}$, Ta = 25°C

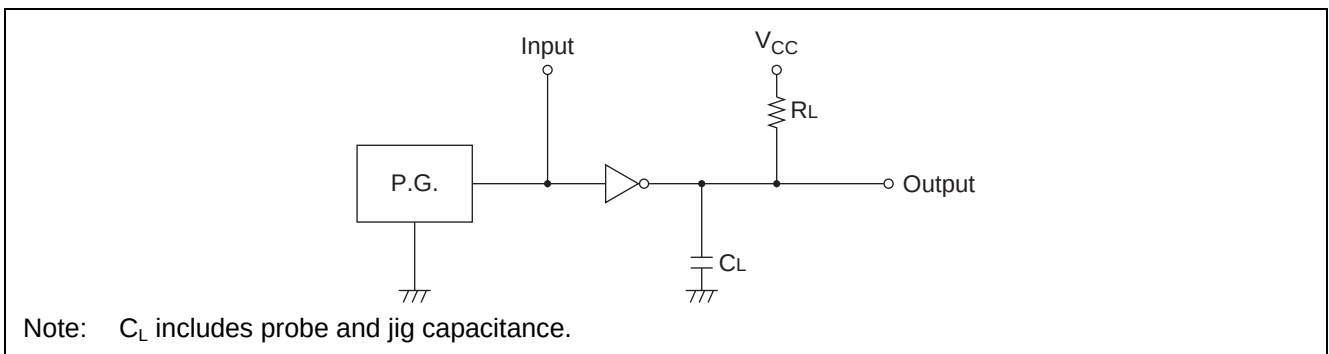
Switching Characteristics

(V_{CC} = 5 V, Ta = 25°C)

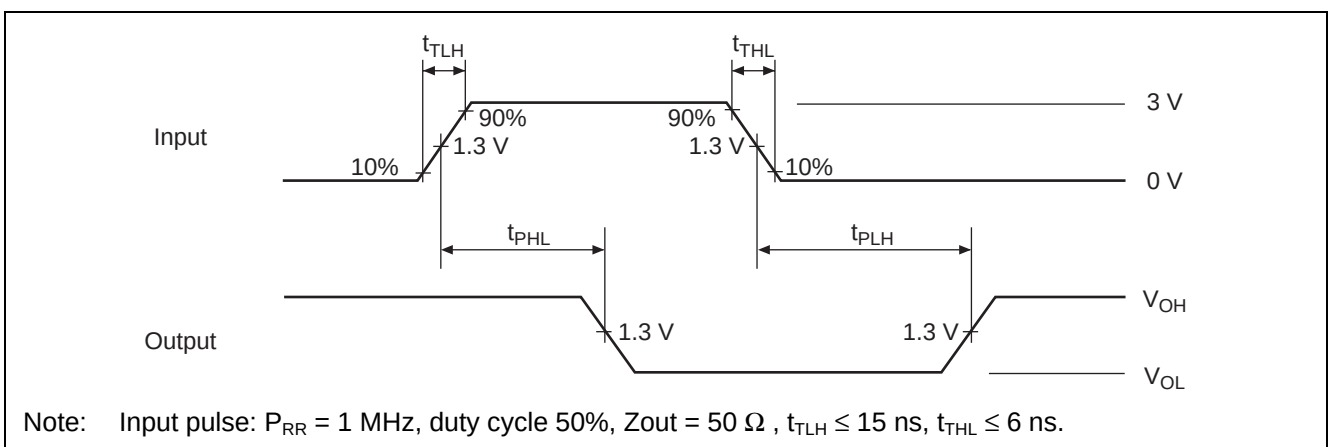
Item	Symbol	min.	typ.	max.	Unit	Condition
Propagation delay time	t_{PLH}	—	10	15	ns	$C_L = 15 \text{ pF}, R_L = 110 \Omega$
	t_{PHL}	—	15	23	ns	

Testing Method

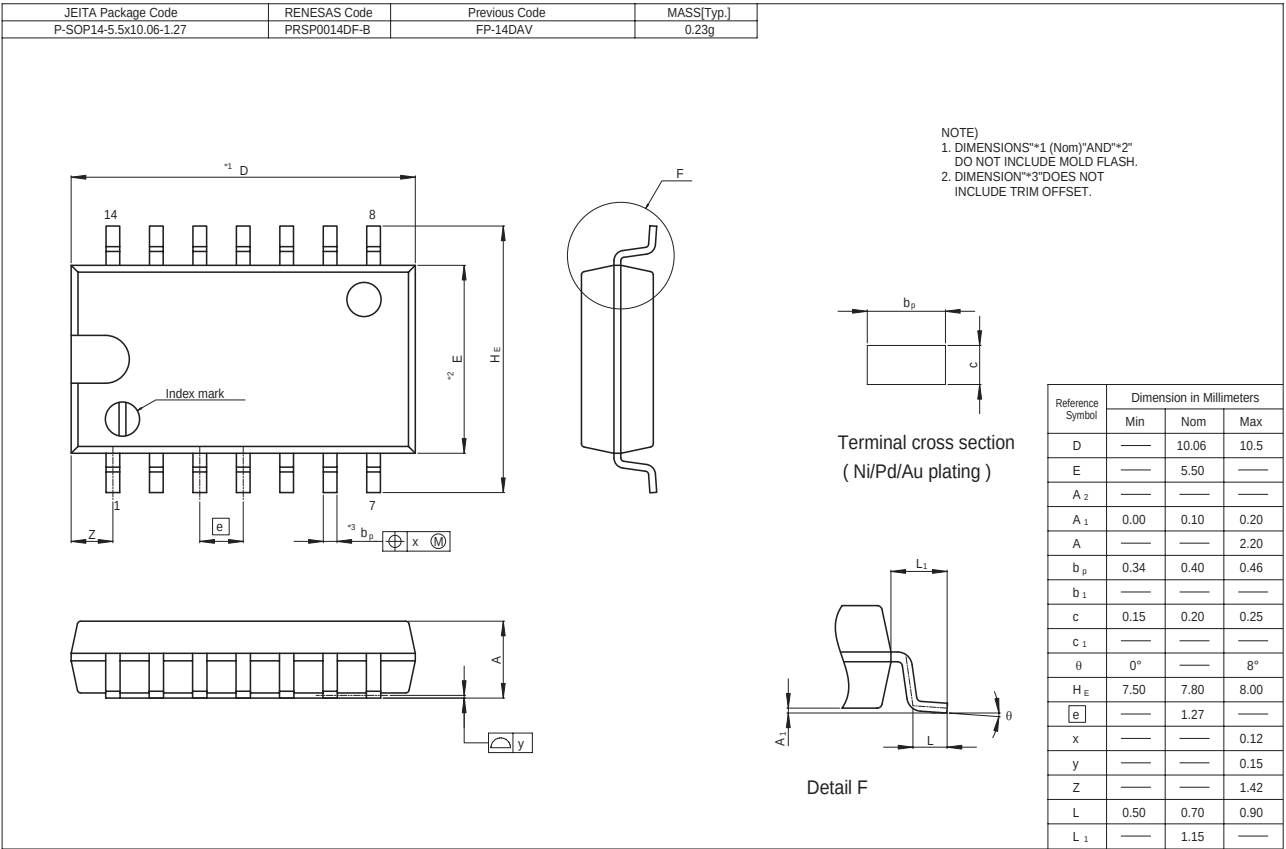
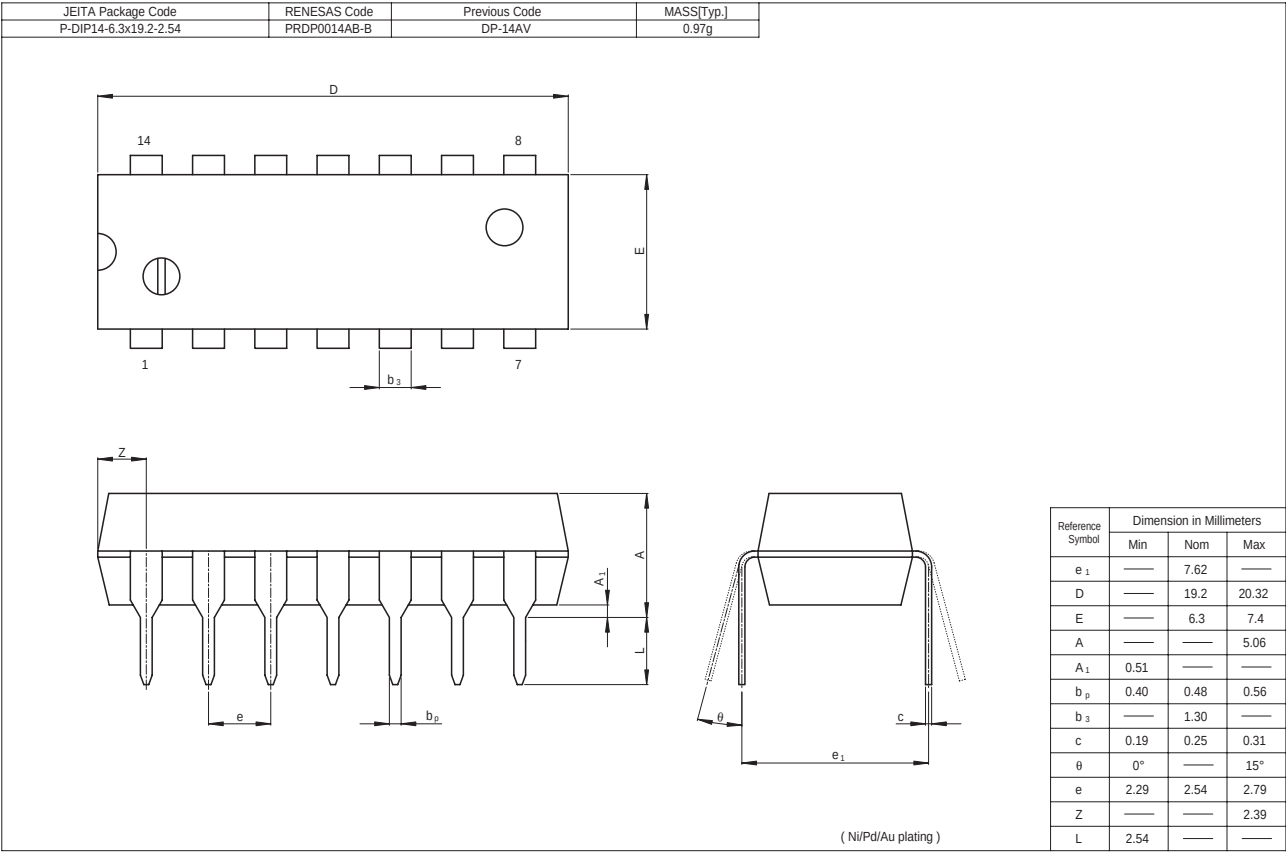
Test Circuit



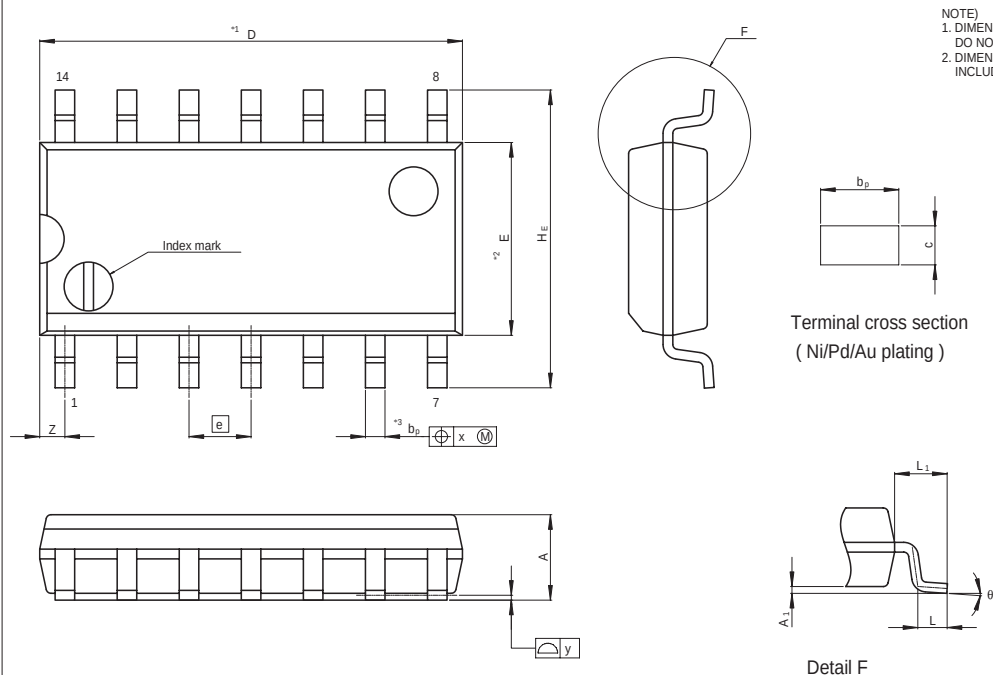
Waveform



Package Dimensions



JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP14-3.95x8.65-1.27	PRSP0014DE-A	FP-14DNV	0.13g



NOTE)
1. DIMENSIONS**1 (Nom)**AND**2*
DO NOT INCLUDE MOLD FLASH.
2. DIMENSION**3*DOES NOT
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	8.65	9.05
E	—	3.95	—
A ₂	—	—	—
A ₁	0.10	0.14	0.25
A	—	—	1.75
b _p	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	5.80	6.10	6.20
e	—	1.27	—
x	—	—	0.25
y	—	—	0.15
Z	—	—	0.635
L	0.40	0.60	1.27
L ₁	—	1.08	—

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